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ABSTRACT OF THE DISCLOSURE

10 A process for packaging an electronic device employs  
an insulating protective resin layer produced from one or  
more of the resin compositions: (1) 100 parts of an or-  
ganic solvent-soluble resin having a polysiloxane skel-  
eton and a polar group, 0.5 to 30 parts of an epoxy com-  
pound having an epoxy equivalent of more than 800, and an  
organic solvent; (2) 100 parts of an organic solvent-  
soluble resin having a polysiloxane skeleton and a polar  
15 group, 0.1 to 10 parts of an epoxy compound having an  
epoxy equivalent of 100 to 800, 2 to 30 weight parts of a  
polyvalent isocyanate compound, and an organic solvent;  
and (3) 100 parts of an organic solvent-soluble resin  
having a polysiloxane skeleton and a polar group, 0.1 to  
20 20 parts of an epoxy compound having an epoxy equivalent  
of more than 800, 2 to 30 parts of a polyvalent iso-  
cyanate compound, and an organic solvent.